



Emerging Interconnection Networks Across Scales

Guest Editor:

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Deadline for manuscript
submissions:

closed (15 December 2018)

Message from the Guest Editor

To advance and capture the recent and future innovations in interconnection technology at multiple scales, such as on-chip networks, chip-to-chip interconnections and data center networks, the proposed Special Issue of *JLPEA* will be dedicated towards innovative ways of interconnecting electronic devices. The readers of this Special Issue will be able to familiarize themselves with the recent advances in these technology paradigms, while also discovering the common and disparate issues about these interconnections at these various scales. Original contributions from the following non-exhaustive list of topics are solicited:

- Power efficiency in Network-on-Chip
- Chip-to-chip interconnections
- Interconnections for heterogeneous systems
- Dynamic interconnection networks
- Data center networks
- 3D NoC
- Photonic/optical interconnects
- RF interconnections
- Wireless interconnects
- Millimeter-wave wireless communication for computing platforms
- THz band communications for computing systems
- Security and Privacy in NoC
- Data center network security and privacy
- Congruence of interconnection networks with IoT





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Message from the Editor-in-Chief

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